

TIF™100-20-16S Series thermally conductive interface materials are applied to fill the air gaps between the heating elements and the heat dissipation fins or the metal base. Their flexibility and elasticity make them suited to coat very uneven surfaces. Heat can transmit to the metal housing or dissipation plate from the heating elements or even the entire PCB, which effectively enhances the efficiency and life-time of the heat-generating electronic components.

Typical Properties of TIF™100N-20-16S Series

Color	Blue-Violet	Visual	
Construction	Boron nitride filled silicone elastomer		*****
Thickness range	0.5mm-5.0mm		ASTM D374
Hardness	45 Shore 00		ASTM 2240
Specific Gravity	1.60g/cc		ASTM D297
Operating Temp	-40 ~160 °C		*****
Dielectric Breakdown Voltage	>5500 VAC		ASTM D149
Dielectric Constant@1MHz	2.8MHz		ASTM D150
Volume Resistivity	1.0X10 ¹² Ohm-cm		ASTM D257
Thermal Conductivity	2.0 W/mK		ASTM D5470
	2.0W/mK		GB-T32064
Outgassing (TML)	0.60%		ASTM E595

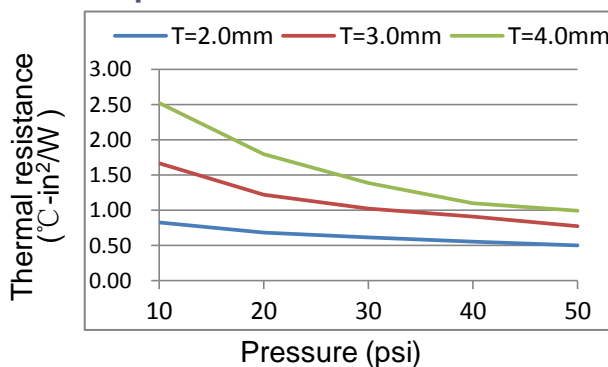
Features

- › Good thermal conductivity: **2.0 W/mK**
- › Naturally tacky needing no further adhesive coating
- › Soft and Compressible for low stress applications
- › Available in varies thickness

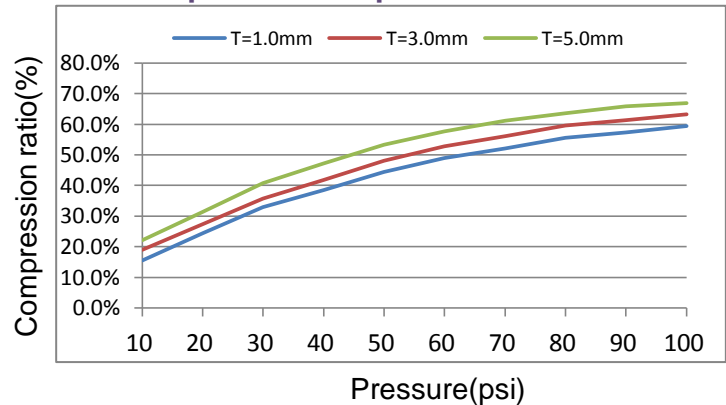
Application

- › Cooling components to the chassis of frame
- › Set Top Box
- › Car Battery & Power Supply
- › Charging Pile
- › LED TV/ Lighting
- › Graphics Card Thermal Module

psi. vs. Thermal Resistance



psi. vs. Compression Ratio



Product Specification

Product Thicknesses

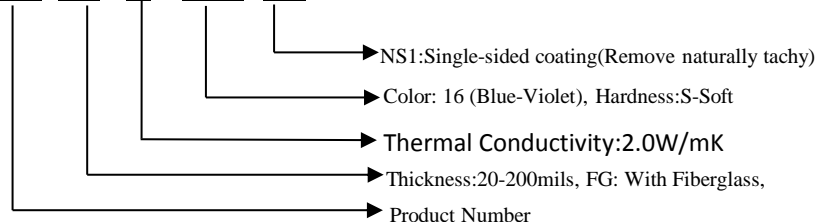
0.020-inch to 0.200-inch (0.5mm to 5.0mm)

Product Sizes

8" x 16"(203mm x406mm)
Individual die cut shapes and custom thickness can be supplied. Please contact us for confirming.

Product Identification:

TIF1 00N - 20 - 16 S - NS1



Thermally Conductive Materials Heat Generating Materials Thermally Conductive Plastics
Foaming Silica Gel Die-Cutting Products

Canada:

Tel: +001-604-2998559
E-mail: sales@thermazig.com

China:

Tel: +86-769-38801208
E-mail: frances@ziitek.com.tw

Taiwan:

Tel: +886-2-22771007
E-mail: frances@ziitek.com.tw

The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assume legal responsibility. Users should undertake sufficient verification and testing to determine the suitability for their own particular purpose of any information or products referred to herein.

Application Technology Download
Thermal Conductive Interface Materials



http://www.ziitek.com